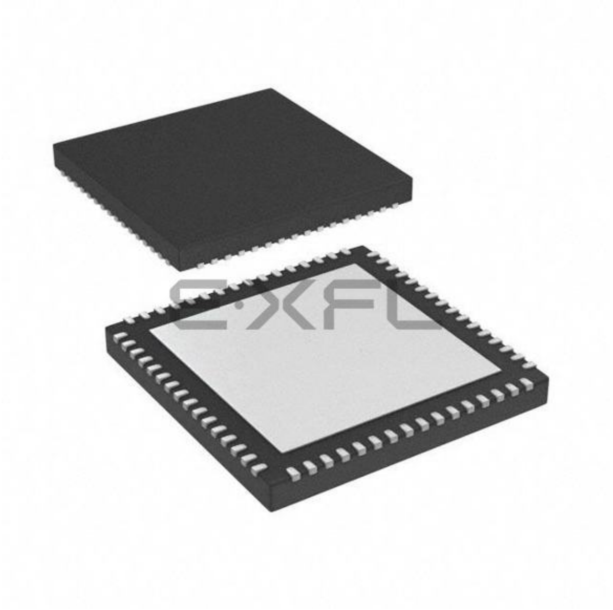

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	49
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 28x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-QFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx230f128ht-i-mr

TABLE 4: PIN NAMES FOR 100-PIN GENERAL PURPOSE DEVICES

100-PIN TQFP (TOP VIEW)

PIC32MX130F128L
PIC32MX150F256L
PIC32MX170F512L

100

1

Pin #	Full Pin Name	Pin #	Full Pin Name
1	AN28/RG15	36	VSS
2	VDD	37	VDD
3	AN22/RPE5/PMD5/RE5	38	TCK/CTED2/RA1
4	AN23/PMD6/RE6	39	AN34/RPF13/SCK3/RF13
5	AN27/PMD7/RE7	40	AN35/RPF12/RF12
6	AN29/RPC1/RC1	41	AN12/PMA11/RB12
7	AN30/RPC2/RC2	42	AN13/PMA10/RB13
8	AN31/RPC3/RC3	43	AN14/RPB14/CTED5/PMA1/RB14
9	RPC4/CTED7/RC4	44	AN15/RPB15/OCFB/CTED6/PMA0/RB15
10	AN16/C1IND/RPG6/SCK2/PMA5/RG6	45	VSS
11	AN17/C1INC/RPG7/PMA4/RG7	46	VDD
12	AN18/C2IND/RPG8/PMA3/RG8	47	AN36/RPD14/RD14
13	$\overline{\text{MCLR}}$	48	AN37/RPD15/SCK4/RD15
14	AN19/C2INC/RPG9/PMA2/RG9	49	RPF4/PMA9/RF4
15	VSS	50	RPF5/PMA8/RF5
16	VDD	51	RPF3/RF3
17	TMS/CTED1/RA0	52	AN38/RPF2/RF2
18	AN32/RPE8/RE8	53	AN39/RPF8/RF8
19	AN33/RPE9/RE9	54	RPF7/RF7
20	AN5/C1INA/RPB5/RB5	55	RPF6/SCK1/INT0/RF6
21	AN4/C1INB/RB4	56	SDA1/RG3
22	PGED3/AN3/C2INA/RPB3/RB3	57	SCL1/RG2
23	PGEC3/AN2/CTCMP/C2INB/RPB2/CTED13/RB2	58	SCL2/RA2
24	PGEC1/AN1/RPB1/CTED12/RB1	59	SDA2/RA3
25	PGED1/AN0/RPB0/RB0	60	TDI/CTED9/RA4
26	PGEC2/AN6/RPB6/RB6	61	TDO/RA5
27	PGED2/AN7/RPB7/CTED3/RB7	62	VDD
28	VREF-/PMA7/RA9	63	OSC1/CLKI/RC12
29	VREF+/PMA6/RA10	64	OSC2/CLKO/RC15
30	AVDD	65	VSS
31	AVSS	66	RPA14/RA14
32	AN8/RPB8/CTED10/RB8	67	RPA15/RA15
33	AN9/RPB9/CTED4/RB9	68	RPD8/RTCC/RD8
34	CVREFOUT/AN10/RPB10/CTED11/PMA13/RB10	69	RPD9/RD9
35	AN11/PMA12/RB11	70	RPD10/PMA15/RD10

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 “Peripheral Pin Select”** for restrictions.

2: Every I/O port pin (RAx-RGx) can be used as a change notification pin (CNAx-CNGx). See **Section 11.0 “I/O Ports”** for more information.

3: Shaded pins are 5V tolerant.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input voltage low (V_{IL}) requirements.

Ensure that the “Communication Channel Select” (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® ICD 3 or MPLAB REAL ICE™.

For more information on MPLAB ICD 3 and MPLAB REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

- *“Using MPLAB® ICD 3”* (poster) DS50001765
- *“MPLAB® ICD 3 Design Advisory”* DS50001764
- *“MPLAB® REAL ICE™ In-Circuit Debugger User’s Guide”* DS50001616
- *“Using MPLAB® REAL ICE™ Emulator”* (poster) DS50001749

2.6 JTAG

The TMS, TDO, TDI and TCK pins are used for testing and debugging according to the Joint Test Action Group (JTAG) standard. It is recommended to keep the trace length between the JTAG connector and the JTAG pins on the device as short as possible. If the JTAG connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

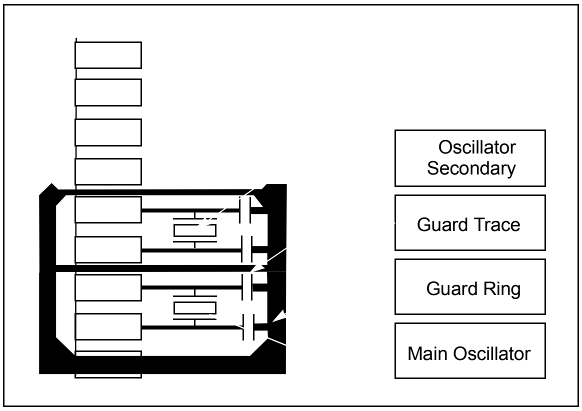
Pull-up resistors, series diodes and capacitors on the TMS, TDO, TDI and TCK pins are not recommended as they will interfere with the programmer or debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input voltage low (V_{IL}) requirements

2.7 External Oscillator Pins

Many MCUs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to **Section 8.0 “Oscillator Configuration”** for details).

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is illustrated in Figure 2-3.

FIGURE 2-3: SUGGESTED OSCILLATOR CIRCUIT PLACEMENT



4.0 MEMORY ORGANIZATION

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX/5XX 64/100-pin family of devices. It is not intended to be a comprehensive reference source.For detailed information, refer to **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

PIC32MX1XX/2XX/5XX 64/100-pin microcontrollers provide 4 GB of unified virtual memory address space. All memory regions, including program, data memory, SFRs and Configuration registers, reside in this address space at their respective unique addresses. The program and data memories can be optionally partitioned into user and kernel memories. In addition, the data memory can be made executable, allowing PIC32MX1XX/2XX/5XX 64/100-pin devices to execute from data memory.

The key features include:

- 32-bit native data width
- Separate User (KUSEG) and Kernel (KSEG0/KSEG1) mode address space
- Flexible program Flash memory partitioning
- Flexible data RAM partitioning for data and program space
- Separate boot Flash memory for protected code
- Robust bus exception handling to intercept runaway code
- Simple memory mapping with Fixed Mapping Translation (FMT) unit

4.1 Memory Layout

PIC32MX1XX/2XX/5XX 64/100-pin microcontrollers implement two address schemes: virtual and physical. All hardware resources, such as program memory, data memory and peripherals, are located at their respective physical addresses. Virtual addresses are exclusively used by the CPU to fetch and execute instructions as well as access peripherals. Physical addresses are used by bus master peripherals, such as DMA and the Flash controller, that access memory independently of the CPU.

The memory maps for the PIC32MX1XX/2XX/5XX 64/100-pin devices are illustrated in Figure 4-1 through Figure 4-4.

6.1 Control Registers

TABLE 6-1: FLASH CONTROLLER REGISTER MAP

Virtual Address (BF80_#)	Register Name	Bit Range	Bits 31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
F400	NVMCON[1]	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	WR	WREN	WRERR	LVDERR	LVDSTAT	—	—	—	—	—	—	—	NVMOP<3:0>				0000
F410	NVMKEY	31:16	NVMKEY<31:0>																0000
		15:0																	0000
F420	NVMADDR[1]	31:16	NVMADDR<31:0>																0000
		15:0																	0000
F430	NVMDATA	31:16	NVMDATA<31:0>																0000
		15:0																	0000
F440	NVMSRC ADDR	31:16	NVMSRCADDR<31:0>																0000
		15:0																	0000

Legend: x = unknown value on Reset; — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 “CLR, SET, and INV Registers”** for more information.

REGISTER 8-1: OSCCON: OSCILLATOR CONTROL REGISTER (CONTINUED)

bit 18-16 **PLLMULT<2:0>:** Phase-Locked Loop (PLL) Multiplier bits

`111` = Clock is multiplied by 24
`110` = Clock is multiplied by 21
`101` = Clock is multiplied by 20
`100` = Clock is multiplied by 19
`011` = Clock is multiplied by 18
`010` = Clock is multiplied by 17
`001` = Clock is multiplied by 16
`000` = Clock is multiplied by 15

bit 15 **Unimplemented:** Read as ‘`0`’

bit 14-12 **COSC<2:0>:** Current Oscillator Selection bits

`111` = Internal Fast RC (FRC) Oscillator divided by OSCCON<FRCDIV> bits
`110` = Internal Fast RC (FRC) Oscillator divided by 16
`101` = Internal Low-Power RC (LPRC) Oscillator
`100` = Secondary Oscillator (SOSC)
`011` = Primary Oscillator (POSC) with PLL module (XTPLL, HSPLL or ECPLL)
`010` = Primary Oscillator (POSC) (XT, HS or EC)
`001` = Internal Fast RC Oscillator with PLL module via Postscaler (FRCPLL)
`000` = Internal Fast RC (FRC) Oscillator

bit 11 **Unimplemented:** Read as ‘`0`’

bit 10-8 **NOSC<2:0>:** New Oscillator Selection bits

`111` = Internal Fast RC Oscillator (FRC) divided by OSCCON<FRCDIV> bits
`110` = Internal Fast RC Oscillator (FRC) divided by 16
`101` = Internal Low-Power RC (LPRC) Oscillator
`100` = Secondary Oscillator (SOSC)
`011` = Primary Oscillator with PLL module (XTPLL, HSPLL or ECPLL)
`010` = Primary Oscillator (XT, HS or EC)
`001` = Internal Fast Internal RC Oscillator with PLL module via Postscaler (FRCPLL)
`000` = Internal Fast Internal RC Oscillator (FRC)

On Reset, these bits are set to the value of the FNOSC Configuration bits (DEVCFG1<2:0>).

bit 7 **CLKLOCK:** Clock Selection Lock Enable bit

If clock switching and monitoring is disabled (FCKSM<1:0> = `1x`):
`1` = Clock and PLL selections are locked
`0` = Clock and PLL selections are not locked and may be modified

If clock switching and monitoring is enabled (FCKSM<1:0> = `0x`):
Clock and PLL selections are never locked and may be modified.

bit 6 **ULOCK:** USB PLL Lock Status bit(1)

`1` = Indicates that the USB PLL module is in lock or USB PLL module start-up timer is satisfied
`0` = Indicates that the USB PLL module is out of lock or USB PLL module start-up timer is in progress or USB PLL is disabled

bit 5 **SLOCK:** PLL Lock Status bit

`1` = PLL module is in lock or PLL module start-up timer is satisfied
`0` = PLL module is out of lock, PLL start-up timer is running or PLL is disabled

bit 4 **SLPEN:** Sleep Mode Enable bit

`1` = Device will enter Sleep mode when a `WAIT` instruction is executed
`0` = Device will enter Idle mode when a `WAIT` instruction is executed

bit 3 **CF:** Clock Fail Detect bit

`1` = FSCM has detected a clock failure
`0` = No clock failure has been detected

Note 1: This bit is available on PIC32MX2XX/5XX devices only.

Note: Writes to this register require an unlock sequence. Refer to **Section 6. “Oscillator”** (DS60001112) in the *“PIC32 Family Reference Manual”* for details.

NOTES:

REGISTER 18-1: I2CxCON: I²C ‘x’ CONTROL REGISTER (‘x’ = 1 AND 2)

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	R/W-0	R/W-1, HC	R/W-0	R/W-0	R/W-0	R/W-0
	ON[1]	—	SIDL	SCLREL	STRICT	A10M	DISSLW	SMEN
7:0	R/W-0	R/W-0	R/W-0	R/W-0, HC	R/W-0, HC	R/W-0, HC	R/W-0, HC	R/W-0, HC
	GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN

Legend:	HC = Cleared in Hardware		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as ‘`0`’

bit 15 **ON:** I²C Enable bit[1]

`1` = Enables the I²C module and configures the SDA and SCL pins as serial port pins
`0` = Disables the I²C module; all I²C pins are controlled by PORT functions

bit 14 **Unimplemented:** Read as ‘`0`’

bit 13 **SIDL:** Stop in Idle Mode bit

`1` = Discontinue module operation when device enters Idle mode
`0` = Continue module operation in Idle mode

bit 12 **SCLREL:** SCLx Release Control bit (when operating as I²C slave)

`1` = Release SCLx clock
`0` = Hold SCLx clock low (clock stretch)

If STREN = `1`:
Bit is R/W (i.e., software can write ‘`0`’ to initiate stretch and write ‘`1`’ to release clock). Hardware clear at beginning of slave transmission. Hardware clear at end of slave reception.

If STREN = `0`:
Bit is R/S (i.e., software can only write ‘`1`’ to release clock). Hardware clear at beginning of slave transmission.

bit 11 **STRICT:** Strict I²C Reserved Address Rule Enable bit

`1` = Strict reserved addressing is enforced. Device does not respond to reserved address space or generate addresses in reserved address space.
`0` = Strict I²C Reserved Address Rule not enabled

bit 10 **A10M:** 10-bit Slave Address bit

`1` = I2CxADD is a 10-bit slave address
`0` = I2CxADD is a 7-bit slave address

bit 9 **DISSLW:** Disable Slew Rate Control bit

`1` = Slew rate control disabled
`0` = Slew rate control enabled

bit 8 **SMEN:** SMBus Input Levels bit

`1` = Enable I/O pin thresholds compliant with SMBus specification
`0` = Disable SMBus input thresholds

Note 1: When using 1:1 PBCLK divisor, the user software should not read/write the peripheral’s SFRs in the SYSCLK cycle immediately following the instruction that clears the module’s ON bit.

REGISTER 20-3: PMADDR: PARALLEL PORT ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CS2(1) ADDR15(2)	CS1(3) ADDR14(4)	ADDR<13:8>					
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ADDR<7:0>							

Legend:

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
-n = Value at POR
‘1’ = Bit is set
‘0’ = Bit is cleared
x = Bit is unknown

bit 31-16 **Unimplemented:** Read as ‘`0`’

bit 15 **CS2:** Chip Select 2 bit(1)
`1` = Chip Select 2 is active
`0` = Chip Select 2 is inactive

bit 15 **ADDR<15>:** Target Address bit 15(2)

bit 14 **CS1:** Chip Select 1 bit(3)
`1` = Chip Select 1 is active
`0` = Chip Select 1 is inactive

bit 14 **ADDR<14>:** Target Address bit 14(4)

bit 13-0 **ADDR<13:0>:** Address bits

Note 1: When the CSF<1:0> bits (PMCON<7:6>) = `10` or `01`.
2: When the CSF<1:0> bits (PMCON<7:6>) = `00`.
3: When the CSF<1:0> bits (PMCON<7:6>) = `10`.
4: When the CSF<1:0> bits (PMCON<7:6>) = `00 or 01`.

Note: If the DUALBUF bit (PMCON<17>) = `0`, the bits in this register control both read and write target addressing. If the DUALBUF bit = `1`, the bits in this register are not used. In this instance, use the PMRADDR register for Read operations and the PMWADDR register for Write operations.

REGISTER 20-10: PMRDIN: PARALLEL PORT READ INPUT DATA REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	RDATAIN<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	RDATAIN<7:0>							

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as ‘0’

bit 15-0 **RDATAIN<15:0>:** Port Read Input Data bits

Note: This register is only used when the DUALBUF bit (PMCON<17>) is set to ‘1’ and exclusively for reads. If the DUALBUF bit is ‘0’, the PMDIN register (Register 20-5) is used for reads instead of PMRDIN.

REGISTER 21-2: RTCALRM: RTC ALARM CONTROL REGISTER (CONTINUED)

bit 7-0 **ARPT<7:0>:** Alarm Repeat Counter Value bits[3]

`11111111` =Alarm will trigger 256 times

•

•

•

`00000000` =Alarm will trigger one time

The counter decrements on any alarm event. The counter only rolls over from 0x00 to 0xFF if CHIME = `1`.

Note 1: Hardware clears the ALRMEN bit anytime the alarm event occurs, when ARPT<7:0> = `00` and CHIME = `0`.

2: This field should not be written when the RTCC ON bit = '`1`' (RTCCON<15>) and ALRMSYNC = `1`.

3: This assumes a CPU read will execute in less than 32 PBCLKs.

Note: This register is reset only on a Power-on Reset (POR).

23.0 CONTROLLER AREA NETWORK (CAN)

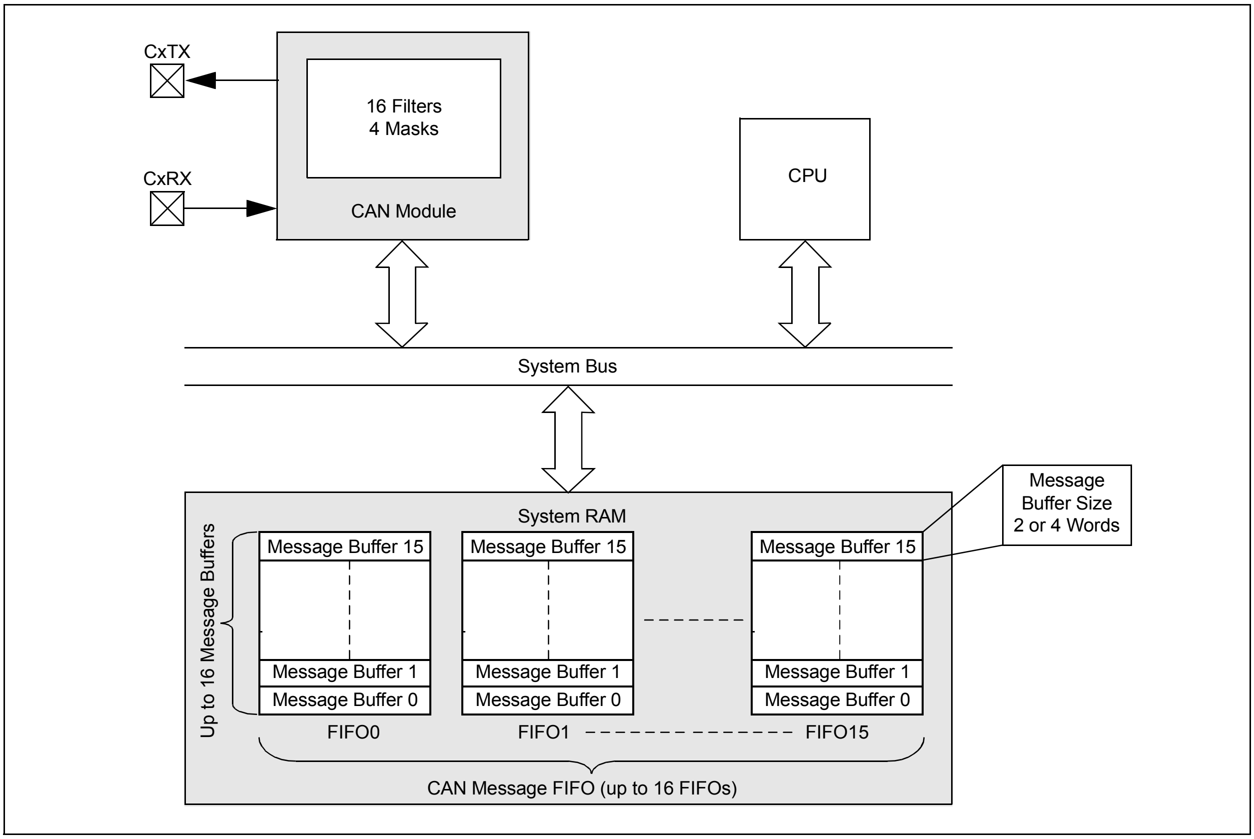
Note: This data sheet summarizes the features of the PIC32MX1XX/2XX/5XX 64/100-pin family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 34. "Controller Area Network (CAN)"** (DS60001154) in the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

The Controller Area Network (CAN) module supports the following key features:

- Standards Compliance:
  - Full CAN 2.0B compliance
  - Programmable bit rate up to 1 Mbps
- Message Reception and Transmission:
  - 16 message FIFOs
  - Each FIFO can have up to 16 messages for a total of 256 messages
  - FIFO can be a transmit message FIFO or a receive message FIFO
  - User-defined priority levels for message FIFOs used for transmission
  - 16 acceptance filters for message filtering
  - Four acceptance filter mask registers for message filtering
  - Automatic response to remote transmit request
  - DeviceNet™ addressing support
- Additional Features:
  - Loopback, Listen All Messages, and Listen Only modes for self-test, system diagnostics and bus monitoring
  - Low-power operating modes
  - CAN module is a bus master on the PIC32 system bus
  - Use of DMA is not required
  - Dedicated time-stamp timer
  - Dedicated DMA channels
  - Data-only Message Reception mode

Figure 23-1 illustrates the general structure of the CAN module.

FIGURE 23-1: PIC32 CAN MODULE BLOCK DIAGRAM



REGISTER 23-7: C1RXOVF: CAN RECEIVE FIFO OVERFLOW STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	RXOVF15	RXOVF14	RXOVF13	RXOVF12	RXOVF11	RXOVF10	RXOVF9	RXOVF8
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	RXOVF7	RXOVF6	RXOVF5	RXOVF4	RXOVF3	RXOVF2	RXOVF1	RXOVF0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as ‘`0`’

bit 15-0 **RXOVF<15:0>:** FIFOx Receive Overflow Interrupt Pending bit

`1` = FIFO has overflowed
`0` = FIFO has not overflowed

REGISTER 23-8: C1TMR: CAN TIMER REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CANTS<15:8>							
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CANTS<7:0>							
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CANTSPRE<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CANTSPRE<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-0 **CANTS<15:0>:** CAN Time Stamp Timer bits

This is a free-running timer that increments every CANTSPRE system clocks when the CANCAP bit (C1CON<20>) is set.

bit 15-0 **CANTSPRE<15:0>:** CAN Time Stamp Timer Prescaler bits

`1111 1111 1111 1111` = CAN time stamp timer (CANTS) increments every 65,535 system clocks
•
•
•
`0000 0000 0000 0000` = CAN time stamp timer (CANTS) increments every system clock

Note 1: C1TMR will be paused when CANCAP = `0`.
2: The C1TMR prescaler count will be reset on any write to C1TMR (CANTSPRE will be unaffected).

REGISTER 23-10: C1FLTCON0: CAN FILTER CONTROL REGISTER 0 (CONTINUED)

bit 20-16 **FSEL2<4:0>:** FIFO Selection bits
`11111` = Reserved
•
•
•
`10000` = Reserved
`01111` = Message matching filter is stored in FIFO buffer 15
•
•
•
`00000` = Message matching filter is stored in FIFO buffer 0

bit 15 **FLTEN1:** Filter 1 Enable bit
`1` = Filter is enabled
`0` = Filter is disabled

bit 14-13 **MSEL1<1:0>:** Filter 1 Mask Select bits
`11` = Acceptance Mask 3 selected
`10` = Acceptance Mask 2 selected
`01` = Acceptance Mask 1 selected
`00` = Acceptance Mask 0 selected

bit 12-8 **FSEL1<4:0>:** FIFO Selection bits
`11111` = Reserved
•
•
•
`10000` = Reserved
`01111` = Message matching filter is stored in FIFO buffer 15
•
•
•
`00000` = Message matching filter is stored in FIFO buffer 0

bit 7 **FLTEN0:** Filter 0 Enable bit
`1` = Filter is enabled
`0` = Filter is disabled

bit 6-5 **MSEL0<1:0>:** Filter 0 Mask Select bits
`11` = Acceptance Mask 3 selected
`10` = Acceptance Mask 2 selected
`01` = Acceptance Mask 1 selected
`00` = Acceptance Mask 0 selected

bit 4-0 **FSEL0<4:0>:** FIFO Selection bits
`11111` = Reserved
•
•
•
`10000` = Reserved
`01111` = Message matching filter is stored in FIFO buffer 15
•
•
•
`00000` = Message matching filter is stored in FIFO buffer 0

Note: The bits in this register can only be modified if the corresponding filter enable (FLTENn) bit is ‘`0`’.

REGISTER 23-12: C1FLTCON2: CAN FILTER CONTROL REGISTER 2 (CONTINUED)

bit 20-16 **FSEL10<4:0>:** FIFO Selection bits

`11111` = Reserved
•
•
•
`10000` = Reserved
`01111` = Message matching filter is stored in FIFO buffer 15
•
•
•
`00000` = Message matching filter is stored in FIFO buffer 0

bit 15 **FLTEN9:** Filter 9 Enable bit

`1` = Filter is enabled
`0` = Filter is disabled

bit 14-13 **MSEL9<1:0>:** Filter 9 Mask Select bits

`11` = Acceptance Mask 3 selected
`10` = Acceptance Mask 2 selected
`01` = Acceptance Mask 1 selected
`00` = Acceptance Mask 0 selected

bit 12-8 **FSEL9<4:0>:** FIFO Selection bits

`11111` = Reserved
•
•
•
`10000` = Reserved
`01111` = Message matching filter is stored in FIFO buffer 15
•
•
•
`00000` = Message matching filter is stored in FIFO buffer 0

bit 7 **FLTEN8:** Filter 8 Enable bit

`1` = Filter is enabled
`0` = Filter is disabled

bit 6-5 **MSEL8<1:0>:** Filter 8 Mask Select bits

`11` = Acceptance Mask 3 selected
`10` = Acceptance Mask 2 selected
`01` = Acceptance Mask 1 selected
`00` = Acceptance Mask 0 selected

bit 4-0 **FSEL8<4:0>:** FIFO Selection bits

`11111` = Reserved
•
•
•
`10000` = Reserved
`01111` = Message matching filter is stored in FIFO buffer 15
•
•
•
`00000` = Message matching filter is stored in FIFO buffer 0

Note: The bits in this register can only be modified if the corresponding filter enable (FLTENn) bit is ‘`0`’.

REGISTER 28-1: DEVCFG0: DEVICE CONFIGURATION WORD 0

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	r-0	r-1	r-1	R/P	r-1	r-1	r-1	R/P
	—	—	—	CP	—	—	—	BWP
23:16	r-1	r-1	r-1	r-1	R/P	R/P	R/P	R/P
	—	—	—	—	PWP<9:6>			
15:8	R/P	R/P	R/P	R/P	R/P	R/P	r-1	r-1
	PWP<5:0>						—	—
7:0	r-1	r-1	r-1	R/P	R/P	R/P	R/P	R/P
	—	—	—	ICESEL<1:0>		JTAGEN[1]	DEBUG<1:0>	

Legend:	r = Reserved bit	P = Programmable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31 **Reserved:** Write ‘`0`’

bit 30-29 **Reserved:** Write ‘`1`’

bit 28 **CP:** Code-Protect bit

Prevents boot and program Flash memory from being read or modified by an external programming device.
`1` = Protection is disabled
`0` = Protection is enabled

bit 27-25 **Reserved:** Write ‘`1`’

bit 24 **BWP:** Boot Flash Write-Protect bit

Prevents boot Flash memory from being modified during code execution.
`1` = Boot Flash is writable
`0` = Boot Flash is not writable

bit 23-20 **Reserved:** Write ‘`1`’

Note 1: This bit sets the value for the JTAGEN bit in the CFGCON register.

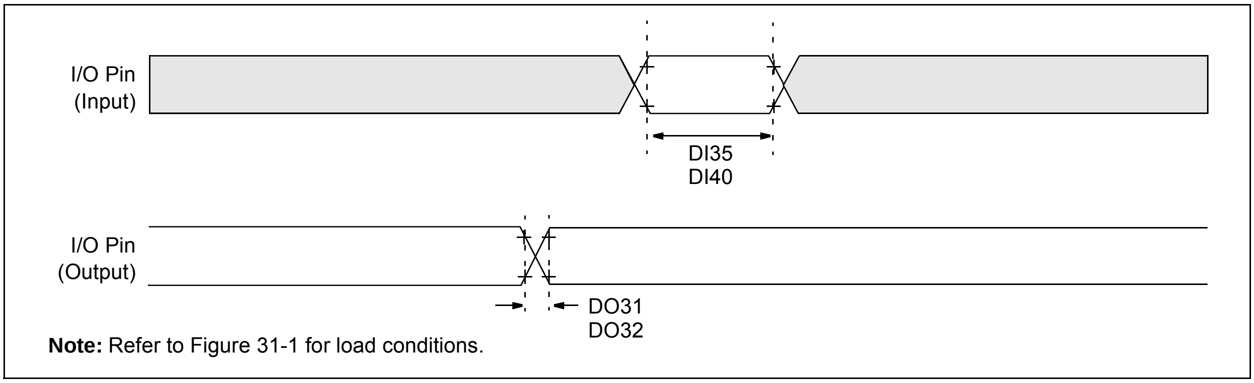
29.0 INSTRUCTION SET

The PIC32MX1XX/2XX/5XX 64/100-pin family instruction set complies with the MIPS32® Release 2 instruction set architecture. The PIC32 device family does not support the following features:

- Core extend instructions
- Coprocessor 1 instructions
- Coprocessor 2 instructions

> **Note:** Refer to *"MIPS32® Architecture for Programmers Volume II: The MIPS32® Instruction Set"* at www.imgtec.com for more information.

FIGURE 31-3: I/O TIMING CHARACTERISTICS



Note: Refer to Figure 31-1 for load conditions.

TABLE 31-21: I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics[2]**	**Min.**	**Typical[1]**	**Max.**	**Units**	**Conditions**
DO31	TIOR	Port Output Rise Time	—	5	15	ns	VDD < 2.5V
			—	5	10	ns	VDD > 2.5V
DO32	TIOF	Port Output Fall Time	—	5	15	ns	VDD < 2.5V
			—	5	10	ns	VDD > 2.5V
DI35	TINP	INTx Pin High or Low Time	10	—	—	ns	—
DI40	TRBP	CNx High or Low Time (input)	2	—	—	TSYSCLK	—

Note 1: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated.

2: This parameter is characterized, but not tested in manufacturing.

FIGURE 31-13: SPIx MODULE SLAVE MODE (CKE = 1) TIMING CHARACTERISTICS

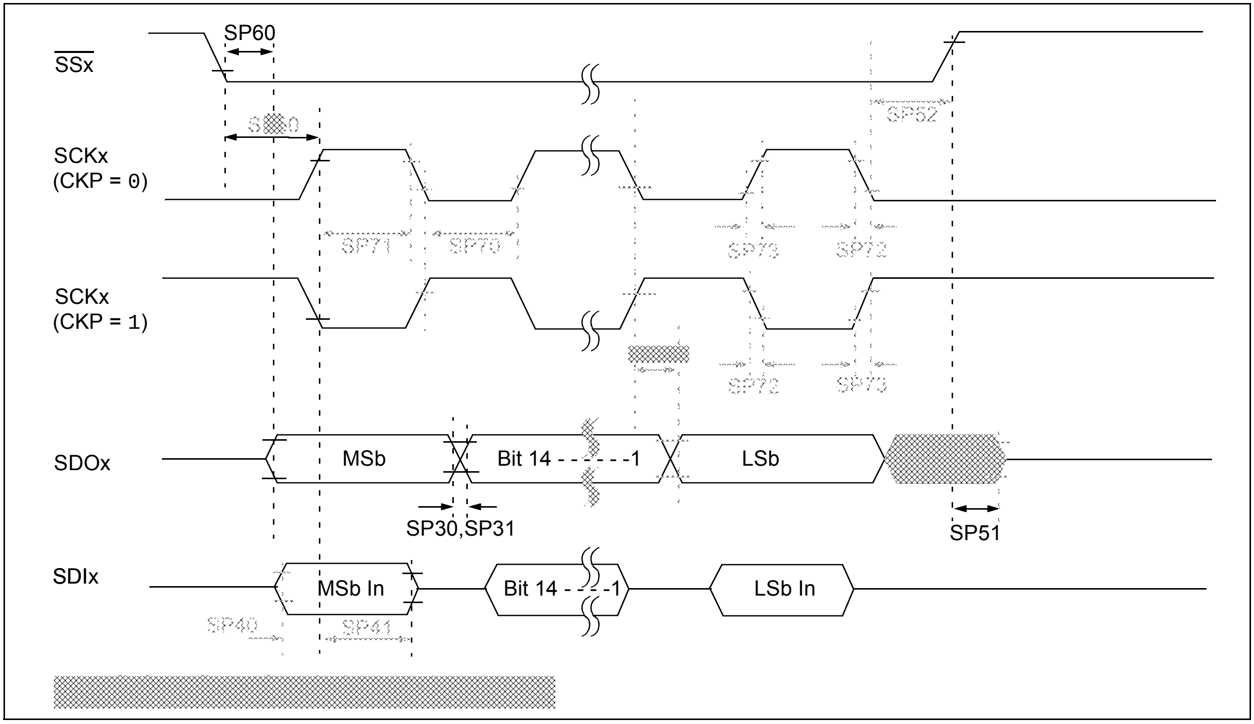


TABLE 31-31: SPIx MODULE SLAVE MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics[1]**	**Min.**	**Typical[2]**	**Max.**	**Units**	**Conditions**
SP70	TscL	SCKx Input Low Time **(Note 3)**	Tsck/2	—	—	ns	—
SP71	TscH	SCKx Input High Time **(Note 3)**	Tsck/2	—	—	ns	—
SP72	TscF	SCKx Input Fall Time	—	5	10	ns	—
SP73	TscR	SCKx Input Rise Time	—	5	10	ns	—
SP30	TdoF	SDOx Data Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	20	ns	VDD > 2.7V
			—	—	30	ns	VDD < 2.7V
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP50	TssL2scH, TssL2scL	$\overline{\text{SSx}}$ ↓ to SCKx ↓ or SCKx ↑ Input	175	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 50 ns.

4: Assumes 50 pF load on all SPIx pins.

TABLE 31-33: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE)

AC CHARACTERISTICS				**Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +105°C for V-temp			
Param. No.	**Symbol**	**Characteristics**		**Min.**	**Max.**	**Units**	**Conditions**
IS10	$T_{LO:SCL}$	Clock Low Time	100 kHz mode	4.7	—	µs	PBCLK must operate at a minimum of 800 kHz
			400 kHz mode	1.3	—	µs	PBCLK must operate at a minimum of 3.2 MHz
			1 MHz mode **(Note 1)**	0.5	—	µs	—
IS11	$T_{HI:SCL}$	Clock High Time	100 kHz mode	4.0	—	µs	PBCLK must operate at a minimum of 800 kHz
			400 kHz mode	0.6	—	µs	PBCLK must operate at a minimum of 3.2 MHz
			1 MHz mode **(Note 1)**	0.5	—	µs	—
IS20	$T_{F:SCL}$	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	C_B is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 C_B	300	ns	
			1 MHz mode **(Note 1)**	—	100	ns	
IS21	$T_{R:SCL}$	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	C_B is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 C_B	300	ns	
			1 MHz mode **(Note 1)**	—	300	ns	
IS25	$T_{SU:DAT}$	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode **(Note 1)**	100	—	ns	
IS26	$T_{HD:DAT}$	Data Input Hold Time	100 kHz mode	0	—	ns	—
			400 kHz mode	0	0.9	µs	
			1 MHz mode **(Note 1)**	0	0.3	µs	
IS30	$T_{SU:STA}$	Start Condition Setup Time	100 kHz mode	4700	—	ns	Only relevant for Repeated Start condition
			400 kHz mode	600	—	ns	
			1 MHz mode **(Note 1)**	250	—	ns	
IS31	$T_{HD:STA}$	Start Condition Hold Time	100 kHz mode	4000	—	ns	After this period, the first clock pulse is generated
			400 kHz mode	600	—	ns	
			1 MHz mode **(Note 1)**	250	—	ns	
IS33	$T_{SU:STO}$	Stop Condition Setup Time	100 kHz mode	4000	—	ns	—
			400 kHz mode	600	—	ns	
			1 MHz mode **(Note 1)**	600	—	ns	

Note 1: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

32.1 DC Characteristics

TABLE 32-1: OPERATING MIPS VS. VOLTAGE

Characteristic	VDD Range (in Volts)[1]	Temp. Range (in °C)	Max. Frequency
			PIC32MX1XX/2XX/5XX 64/100-pin Family
MDC5	VBOR-3.6V	-40°C to +85°C	50 MHz

Note 1: Overall functional device operation at VBORMIN < VDD < VDDMIN is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below VDDMIN. Refer to parameter BO10 in Table 31-10 for BOR values.

TABLE 32-2: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial	
Parameter No.	**Typical[3]**	**Max.**	**Units**	**Conditions**
Operating Current (IDD) (Note 1, 2)				
MDC24	25	40	mA	50 MHz

Note 1: A device's IDD supply current is mainly a function of the operating voltage and frequency. Other factors, such as PBCLK (Peripheral Bus Clock) frequency, number of peripheral modules enabled, internal code execution pattern, execution from Program Flash memory vs. SRAM, I/O pin loading and switching rate, oscillator type, as well as temperature, can have an impact on the current consumption.

2: The test conditions for IDD measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU, Program Flash, and SRAM data memory are operational, SRAM data memory Wait states = `1`
- No peripheral modules are operating, (ON bit = `0`), but the associated PMD bit is cleared
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{\text{MCLR}}$ = VDD
- CPU executing `while(1)` statement from Flash

3: RTCC and JTAG are disabled

4: Data in "Typical" column is at 3.3V, 25°C at specified operating frequency unless otherwise stated. Parameters are for design guidance only and are not tested.